

ABSTRACT OF THE DISCLOSURE

CIRCUIT BOARDS USING HEAT RESISTANT RESIN
FOR ADHESIVE LAYERS

An adhesive composition comprising (a) a polyamide-imide resin preferably having a molecular weight of 80,000 or more and (b) a thermosetting component preferably comprising an epoxy resin and a curing agent and/or a curing accelerator therefor is used for providing an insulating adhesive layer having a storage elastic modulus at 300°C of 30 MPa or more and a glass transition temperature of 180°C or higher, said insulating adhesive being suitable for use in wire scribed circuit boards, multilayer printed circuit boards, and circuit boards for chip carriers.

(Figure 4I)



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